# 2SK2328

# Silicon N-Channel MOS FET

# HITACHI

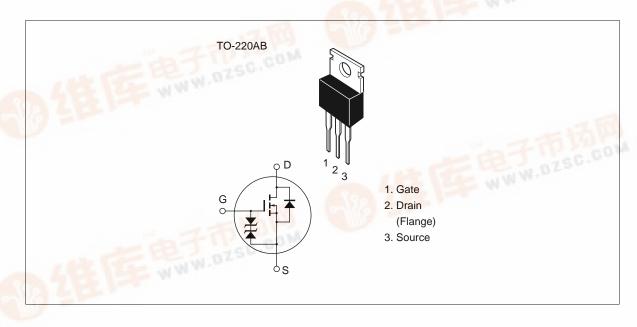
### Application

High speed power switching

#### **Features**

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switchingregulator, DC-DC converter

#### Outline





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# Absolute Maximum Ratings ( $Ta = 25^{\circ}C$ )

Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DSS</sub>	650	V
Gate to source voltage	$V_{\rm GSS}$	±30	V
Drain current	I <sub>D</sub>	7	A
Drain peak current	I <sub>D(pulse)</sub> *1	28	A
Body to drain diode reverse drain current	I <sub>DR</sub>	7	A
Channel dissipation	Pch*2	75	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1 %

2. Value at Tc = 25 °C

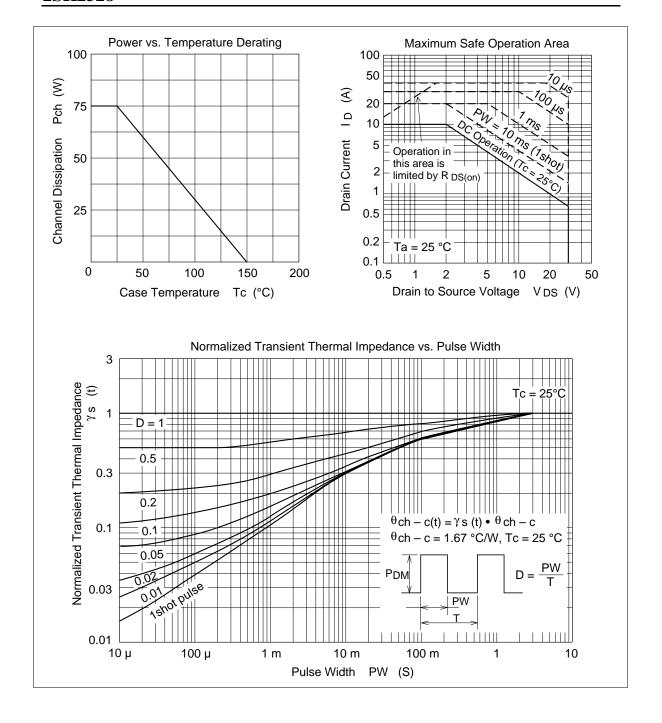
# **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	650	_	_	V	$I_{D} = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	250	μΑ	$V_{DS} = 550 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	_	3.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	$R_{DS(on)}$	_	1.0	1.4	Ω	$I_D = 4A$ $V_{GS} = 10 \text{ V}^{*1}$
Forward transfer admittance	y <sub>fs</sub>	4.0	6.5	_	S	I <sub>D</sub> = 4 A V <sub>DS</sub> = 10 V* <sup>1</sup>
Input capacitance	Ciss	_	1180	_	pF	V <sub>DS</sub> = 10 V
Output capacitance	Coss	_	265	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	50	_	pF	f = 1 MHz
Turn-on delay time	t <sub>d(on)</sub>	_	15	_	ns	I <sub>D</sub> = 4 A
Rise time	t <sub>r</sub>	_	50	_	ns	V <sub>GS</sub> = 10 V
Turn-off delay time	$t_{\text{d(off)}}$	_	105	_	ns	$R_L = 7.5 \Omega$
Fall time	t <sub>f</sub>	_	45	_	ns	
Body-drain diode forward voltage	$V_{DF}$	_	0.95	_	V	$I_F = 7 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery time	t <sub>rr</sub>	_	420	_	ns	$I_F = 7 \text{ A}, V_{GS} = 0,$ $di_F / dt = 100 \text{ A} / \mu \text{s}$

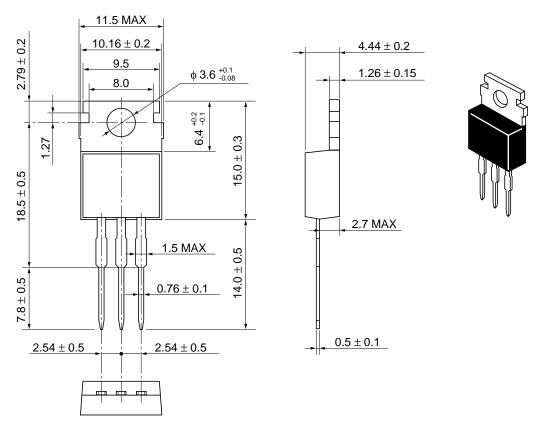
Note 1. Pulse Test

See characteristic curves of 2SK1403A

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